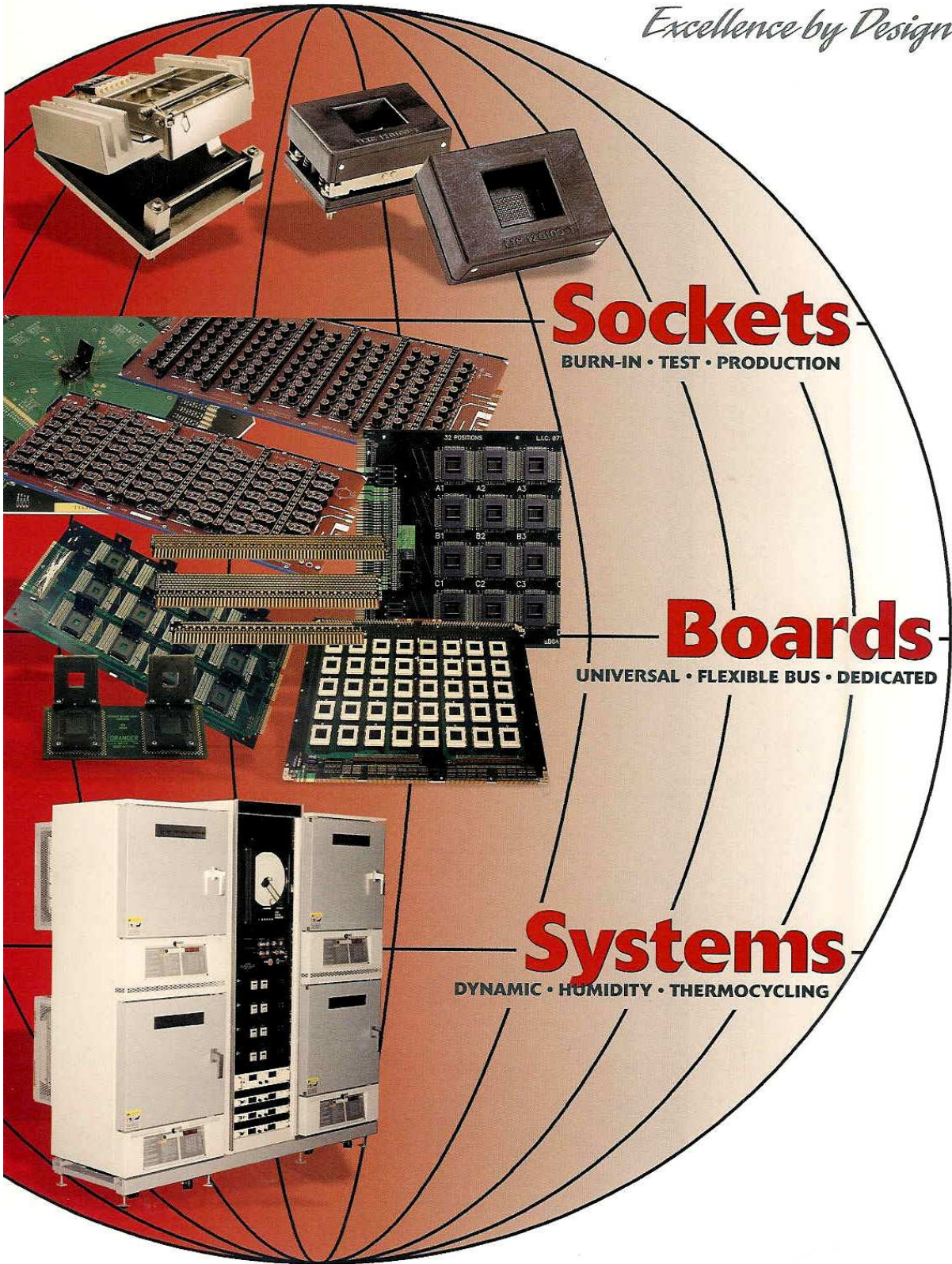


Excellence by Design



Sockets

BURN-IN • TEST • PRODUCTION

Boards

UNIVERSAL • FLEXIBLE BUS • DEDICATED

Systems

DYNAMIC • HUMIDITY • THERMOCYCLING

New Product Overview 2013



QFN Sockets

- *0.25mm Pitch and Greater*
- *Dual Row QFN Socket Options Available*
- *Non-Magnetic Socket Options Available*
- *Accurate, Tightly-controlled Package Fit*
- *Optional Heat Sink and Case Contacts*
- *PTH or Compression Mount Contacts*
- *Optional "Heat Pipe" to Printed Circuit Board*
- *Zero-insertion-force*
- *ClamShell and Open Top Socket Designs*

QFN Sockets



BGA Sockets

- *0.25mm Pitch and Greater*
- *Accommodates Package Height Variations*
- *Non-Magnetic Socket Options Available*
- *Accurate, Tightly-controlled Package Fit*
- *Contacts Connect Solder ball to Board Pad*
- *Optional Heat Sink*
- *Low Profile and Small Footprint*
- *Zero-insertion-force*
- *Surface Mount Design / Solder-Free*

BGA Sockets



Gull Wing Sockets

- *Kelvin, Double Duty Kelvin, and Non Kelvin*
- *Zero Insertion Force Clam Shell Design*
- *Non-Magnetic Socket Options Available*
- *Accurate, Tightly-controlled Package Fit*
- *Optional Case Contacts*
- *Optional Heat Sinking*
- *Fine Pitches*
- *Contact Wiping Action for Reliable Connection*

Gull Wing Sockets



TO Sockets

- *Top-Loading and Clam Shell Designs*
- *Kelvin and Single-Sided Contacts*
- *Small Size Offers Maximum Board Density*
- *Package Standoffs Aid Package Removal*
- *Wide Funnel Entry Guides Package Leads*
- *Positive Contact Wiping Action*
- *Low Profile and Small Footprint*
- *ClamShell Socket Design*

TO Sockets



Surface Mount Device Sockets

- *Top Loading and Clam Shell Designs*
- *Kelvin and Single-Sided Contacts*
- *Zero Insertion Force Clamshell Designs*
- *Low Insertion Force Open Top Designs*
- *Optional Multiple Devices per Socket*
- *0.25 mm pitches and Greater*
- *Distance Between Package Sides with Leads is Defined as the Package Width Dimension*

SMD Sockets



LCC Sockets

- *Easy Loading and Unloading*
- *Positive Contact Wiping Action*
- *Open Top and Clam Shell Designs*
- *0.25 mm and Greater Pitches*
- *Dual Height Contact Options*
- *Live or Dead Bug Loading Options*
- *Low Profile and Small Footprint*
- *Open Top Designs Independent of Package Height*

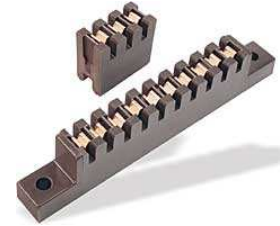
LCC Sockets



Axial and Radial Sockets

- *Kelvin and Non Kelvin Contacts*
- *Building Block Strip Sockets*
- *Accepts Various Lead Diameters*
- *Contact Wiping Action on Lead Diameter*
- *Optional Mounting Ears for Screw Mounting*
- *Modifications Available*
- *Various Pitches Available*

Axial Sockets



LGA Sockets

- *0.25mm Pitch and Greater*
- *Accommodates Package Height Variations*
- *Non-Magnetic Socket Options Available*
- *Accurate, Tightly-controlled Package Fit*
- *Contacts Connect Land pad to Board Pad*
- *Optional Heat Sink*
- *Low Profile and Small Footprint*
- *Zero-insertion-force*
- *Surface Mount Design / Solder-Free*

LGA Sockets



Microwave Sockets

- *Standard and Custom Designs*
- *For Microwave Packages*
- *For Custom Module Packages*
- *Optional 50 Ohm Impedance Designs with Matching Board Layouts*
- *Optional Heat Sinks*
- *Optional Direct Contact of Device Leads onto Board Traces*

Microwave Sockets



Connectors

- *Independent Contacts*
- *Pitches of 0.100", 0.150" and 0.156"*
- *Heavy Duty for Long Life*
- *V Slot Guides Insertion of Board*
- *For Board Thickness of 0.054" to 0.070"*
- *Optional Mounting Ears*
- *Non-Bifurcated Contacts for Increased Current*
- *Positive Wiping Action for Reliable Contact*

Connectors



SIP (Single Inline Package) Sockets

- Kelvin and Non Kelvin
- Top Loading
- For In-line TO and SIP Packages
- Modified and Custom Sockets Available
- May Accommodate More than One Package
- Fit is Independent of Package Body L, W and H
- Various Pitches Available

SIP Sockets



Zig Zag Sockets

- Top-Loading and Clam Shell Designs
- Kelvin and Single-Sided Contacts
- Modified and Custom Sockets Available
- Variety of Pitches and Package Lead Sizes
- For In-line and Zig-Zag Packages
- Positive Contact Wiping Action
- Optional Zero-Insertion Force

Zig Zag Sockets



DIP (Dual Inline Package) Sockets

- Top Loading Designs
- High Side Contacts Help Align Package Leads
- Positive Contact Wiping Action
- Low Insertion Force
- Bottom Socket Standoffs Help Board Cleaning
- Various Sizes and I/O
- Unloading Tool Also Available

DIP Sockets



Optical Transceiver Sockets

- Contact Pitches of 0.25 mm and Greater
- Openings for Fiber Optic Connector
- Clamshell Cover
- Custom Designs Available
- Floating Cover Design
- Compression Mount / Solder-Free Design
- BGA and LGA Styles

Optical Transceiver Sockets



Flat Pack Sockets

- Open Top and Clam Shell Designs
- Accommodate Standard Carriers
- Rugged Construction
- Wire-Formed Contacts
- Solid Clamping of Device Carrier
- Various Sizes and I/O Available

Flat Pack Sockets



PGA Sockets

- Zero Insertion Force
- Small Footprint
- Multi - Point Wiping Contact Action
- Reliable, Normally Closed Contacts

PGA Sockets



Socket Accessories

- *Kelvin Alligator Clips*
- *Up to 175 C Use*
- *Optional Attached Wiring*
- *Reliable, Normally Closed Contacts*
- *Torque Wrench Kits Available for Socket Assembly*
- *Fixed and Variable Torque Wrench Kits*

Socket Accessories



New Product Releases

[Optical Transceiver ClamShell Socket](#) / [SmartSocket](#) / [Dual-Package ClamShell Socket](#)

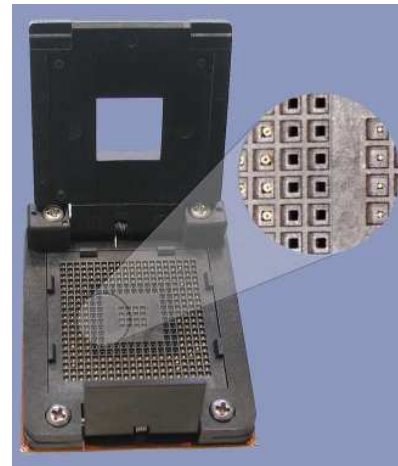
[HAST BGA ClamShell Socket](#) / [High I/O CSP ClamShell Socket](#) / [Double-Duty Kelvin ClamShell Socket](#)

[Quad FlatPak ClamShell Socket](#) / [QFN ClamShell Socket w/Bottom Heatsink](#) / [SmartSocket™ Spec Sheet](#)

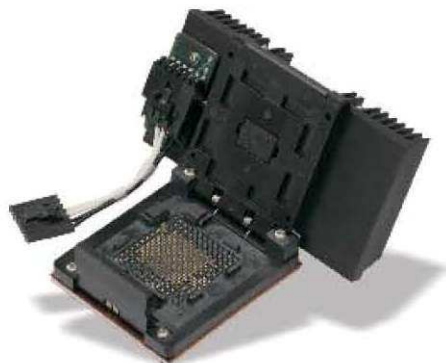
NEW: Loranger Non-magnetic Sockets



Loranger Non-Magnetic Socket Samples



**Loranger Smart Socket
with heater and
temperature sensor for
external control**





B.C.E. s.r.l.
Via Regina Pacis, 54/c - 41049 SASSUOLO (MO) Italy
Tel. +39 0536 811.616 r.a. - Fax +39 0536 811.500
www.bce.it - E-mail: bce@bce.it

